



**APPLICATION SUMMARY**

Semiconductor chips are fragile devices prior to packaging and require delicate handling. During Through-Silicon Via (TSV), eutectic, epoxy, or solder based die attach processes, consistent force must be applied to the the chip. Incorrect force application causes broken chips and incomplete bonds. Load cells incorporated into the die attach tooling enables closed loop control during this delicate process.

**PRODUCTS IN USE**

One LCM100 Miniature In Line Load Cell paired with Instrumentation (IPM650, IDA100, IAA300 Differential Strain Gauge Amplifier)

All FUTEK application illustrations are strictly conceptual. Please contact us with questions.